

The **leading equipment manufacturer** for sub-micron die bonding and advanced SMD rework.

We provide solutions for each stage of your journey - from R&D to industrial automated production.

Neil O'Brien
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...simply accurate



Research & Development



High Yield Production



Electronics Manufacturing

Manual to Fully Automated Bonding Equipment for Prototyping

Research & Development

High Yield Production

FINEPLACER® pico ma



FINEPLACER® lambda 2



FINEPLACER® sigma



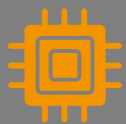
FINEPLACER® femto 2



FINEPLACER® femto^{blu}



High Level of Vertical Integration



Process Competence



Hardware Development



Software Development



In-house Manufacturing



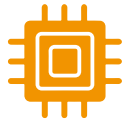
Global Service

 **MADE IN GERMANY**





Served Industries



Process Competence

- » Working with the customer
 - » Process development
 - » Evaluation
 - » Application service
- » 140 m² cleanroom space, ISO class 6-8
- » Entire equipment range available





FINEPLACER® lambda 2

Field of Use

Semi-automated or manual tabletop laboratory bonder for:

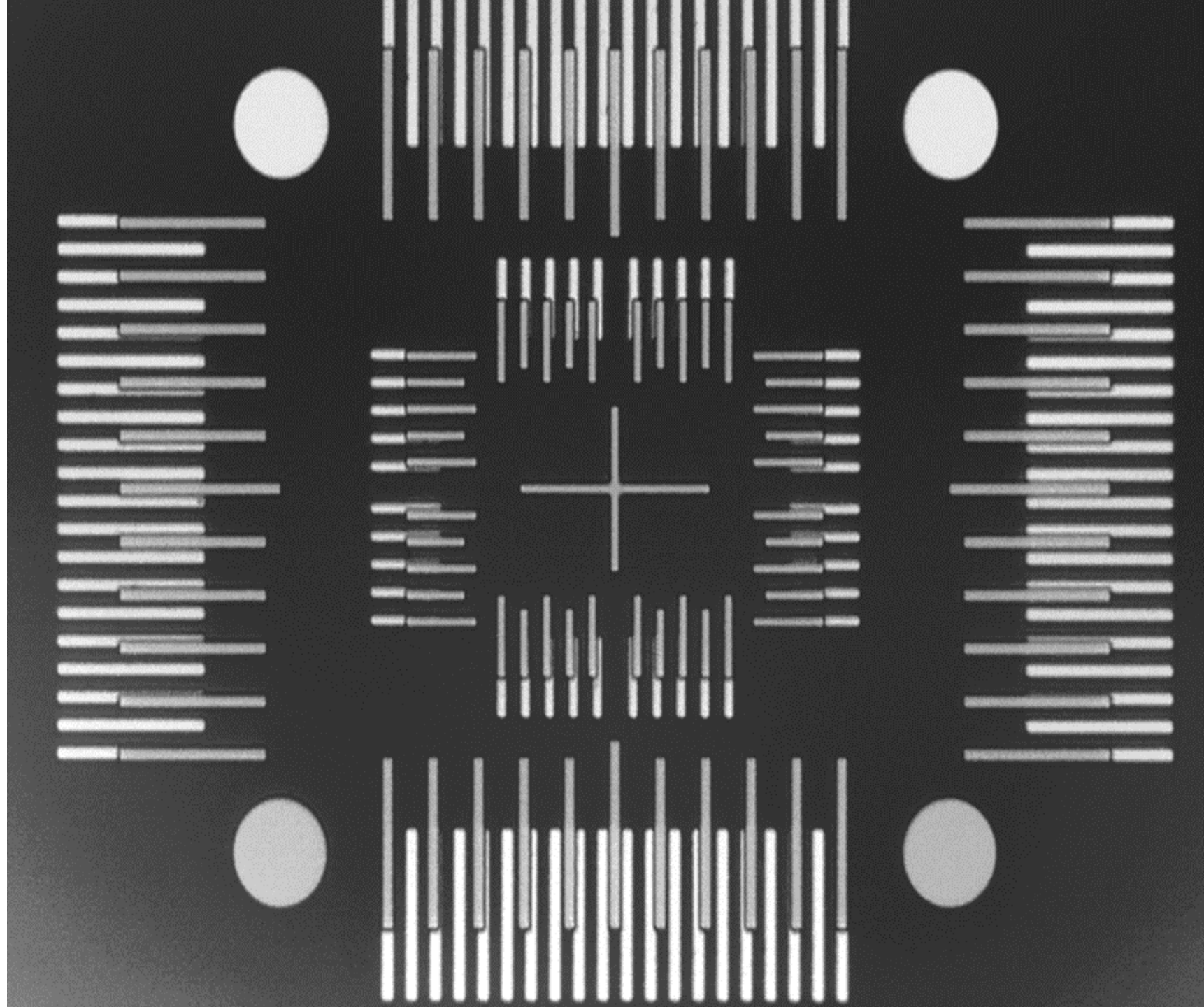
- » Institutes
- » Universities
- » R&D Departments

Operation



Placement Accuracy

- » Simple to use overlay vision alignment system
- » Highest precision assembly



Placement Accuracy

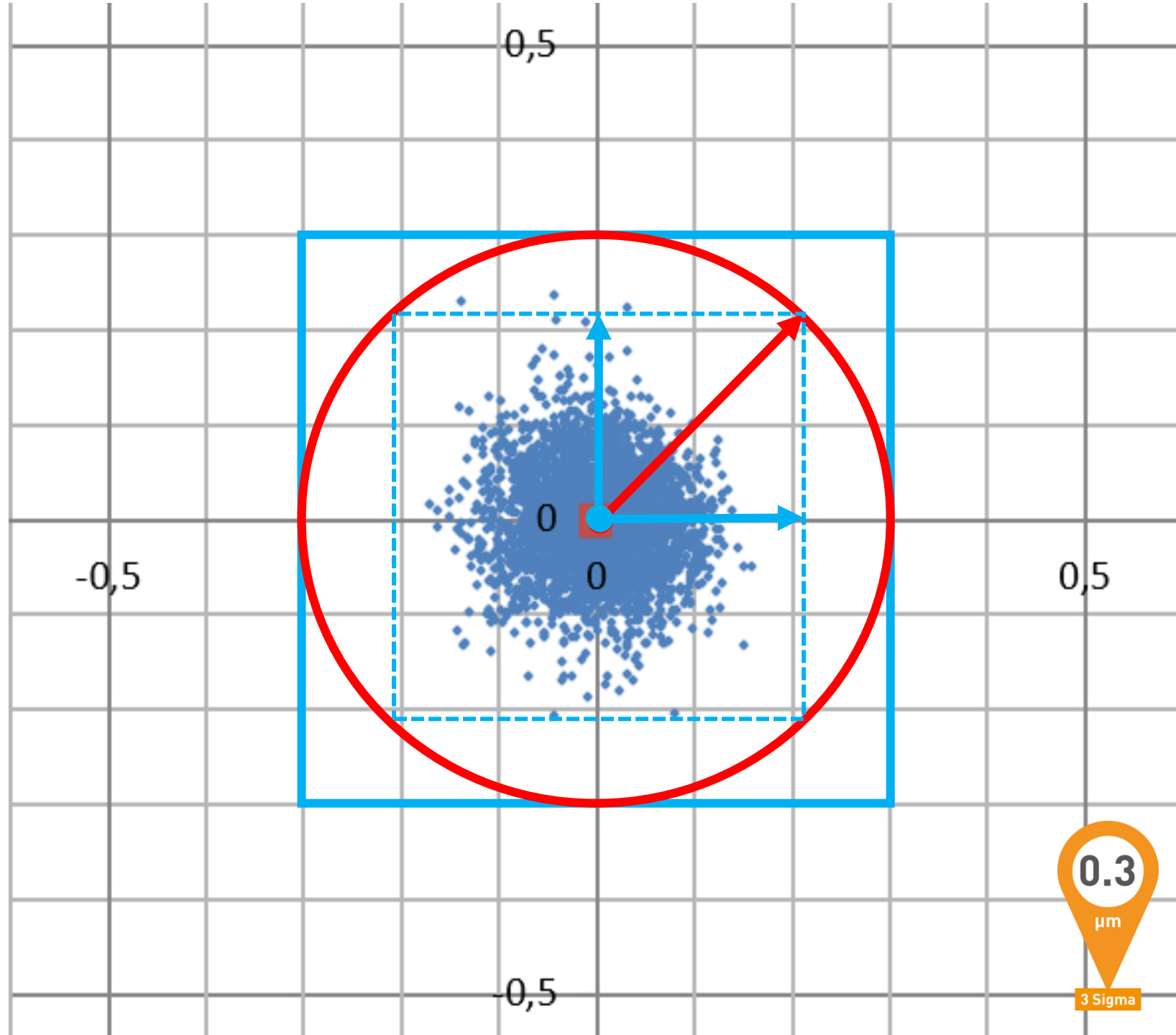
Test results

Cartesian accuracy:

X / Y separate: $<0.3 \mu\text{m}$ @ 3 sigma

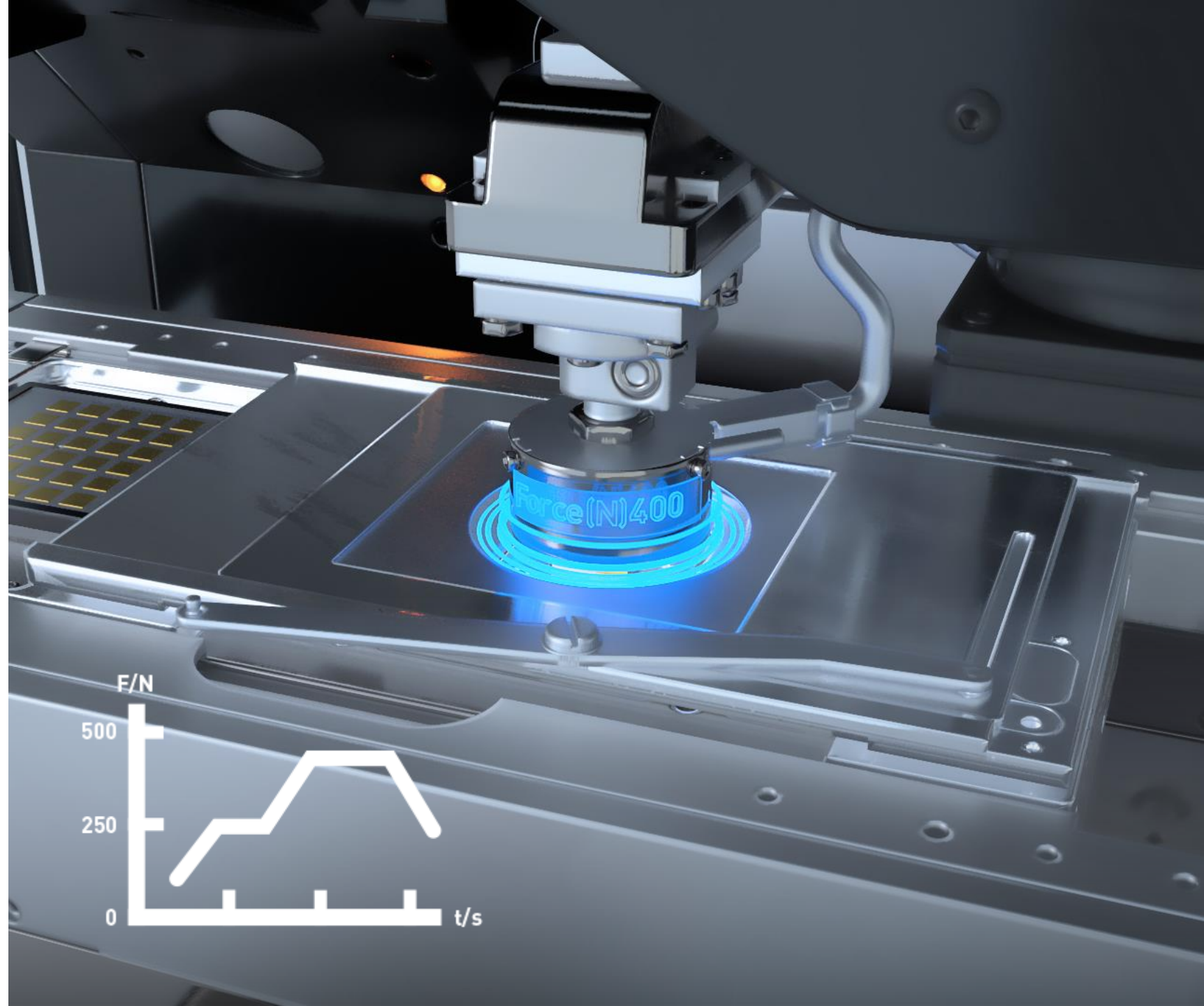
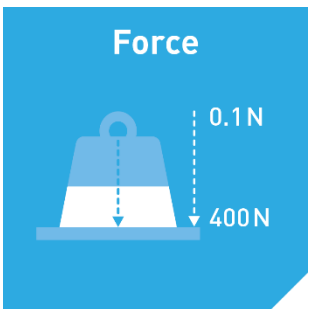
Radial accuracy:

vector based: $0.3 \mu\text{m}$ @ 3 sigma



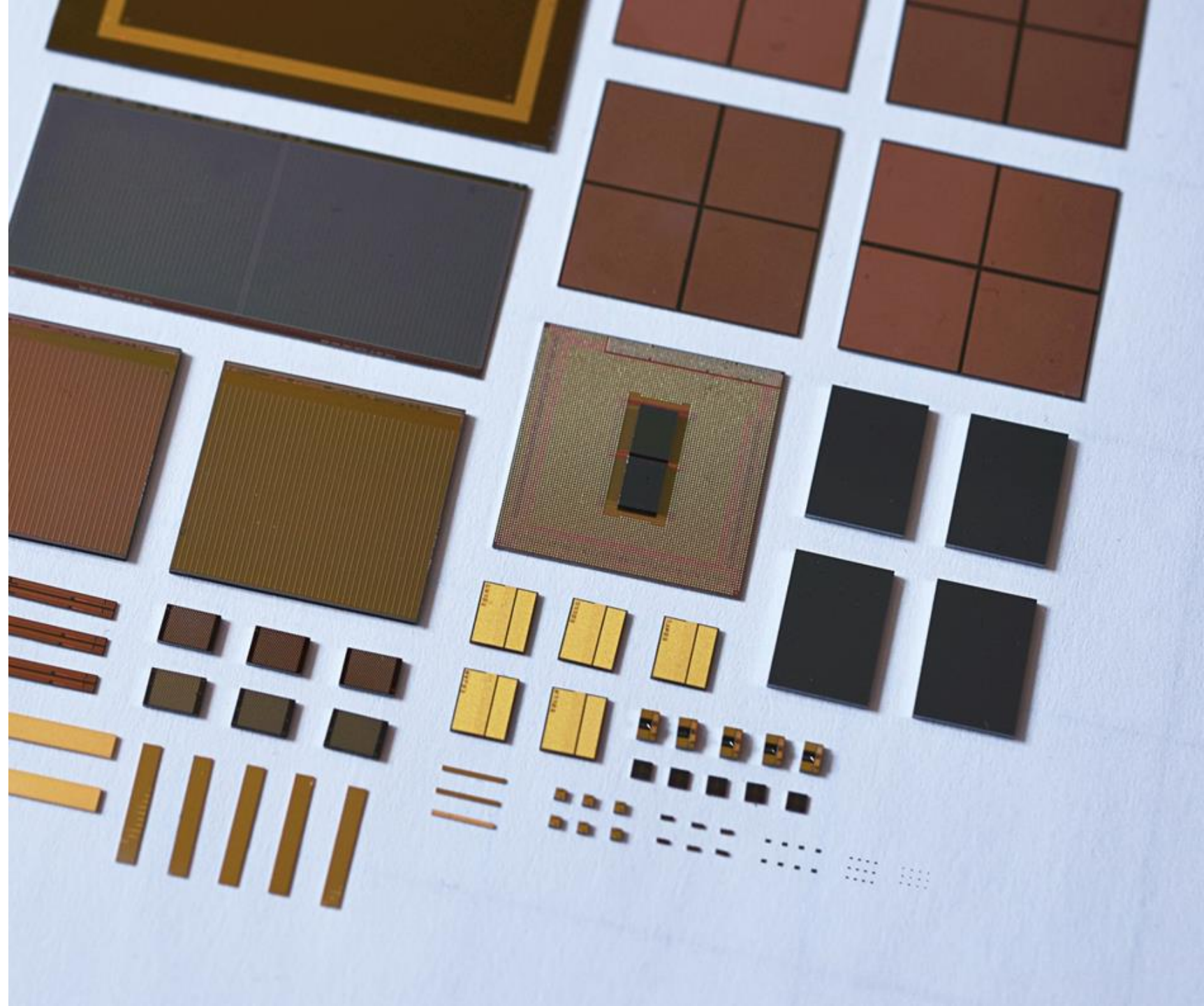
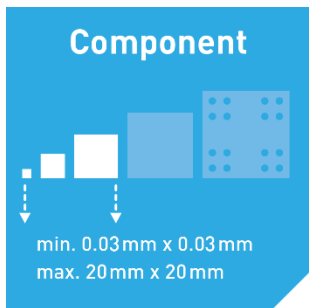
Bonding Force

- » Up to 400 N
- » Variable ramp rates (with motorized Bonding Force Module)
- » Measured and controlled by internal sensors



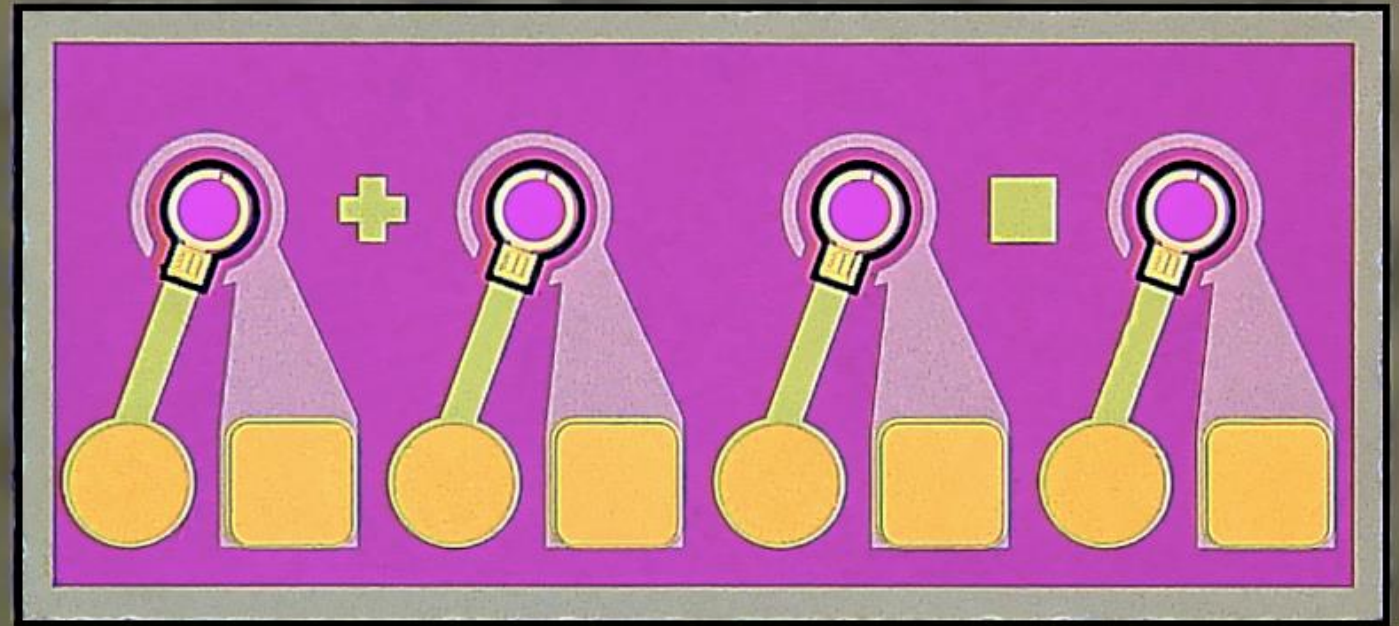
Component Size

- » Small chips with edge lengths of only a few μm
- » Large chips with edge lengths of 20 mm and more
- » And everything in between



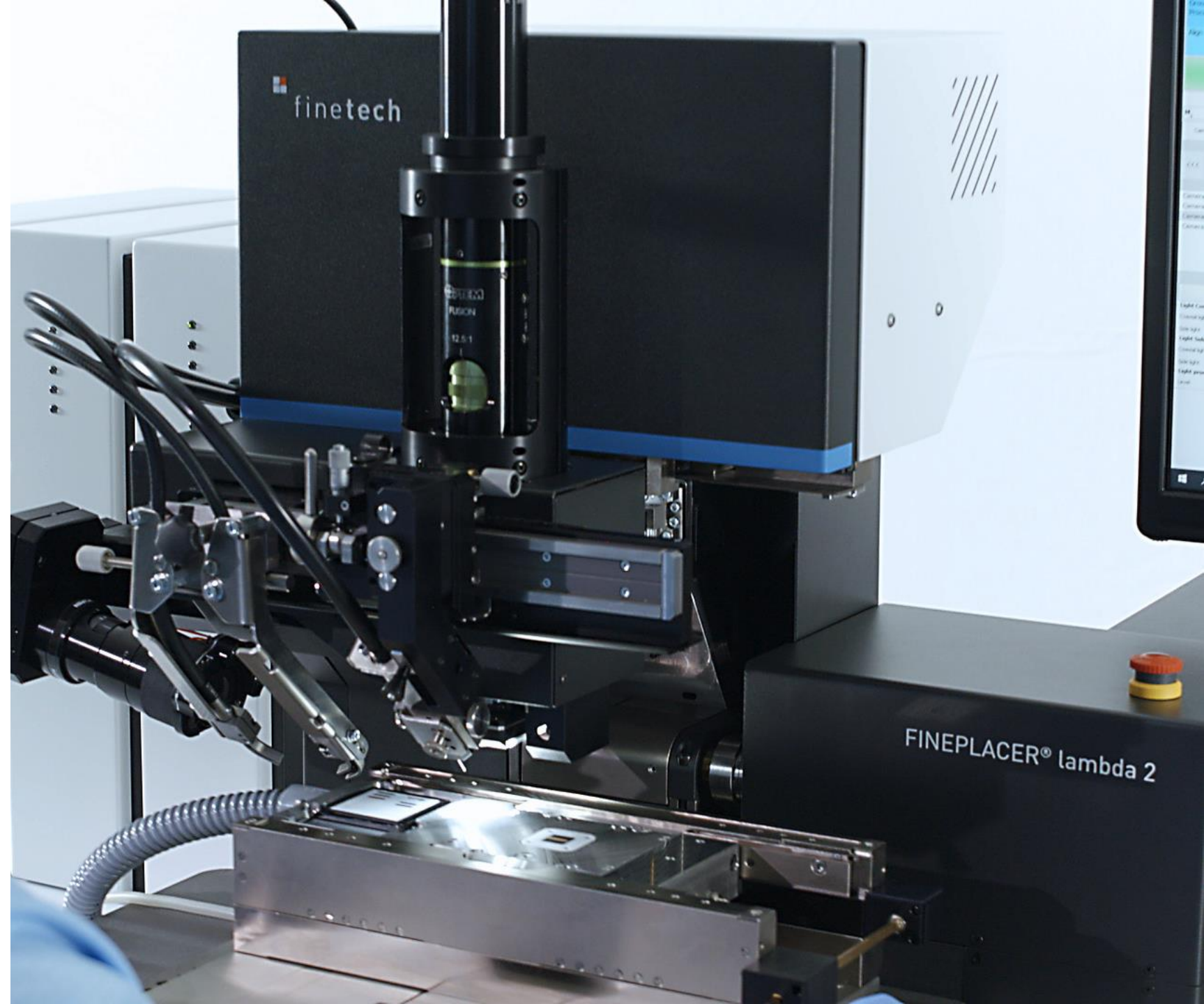
Highest Optical Resolution

- » High quality aperture
- » Adaptable fields of view
- » Controlled lighting settings for chip and target



Instant Operation

- » Fast machine setup
- » Easy handling
- » Fast process development



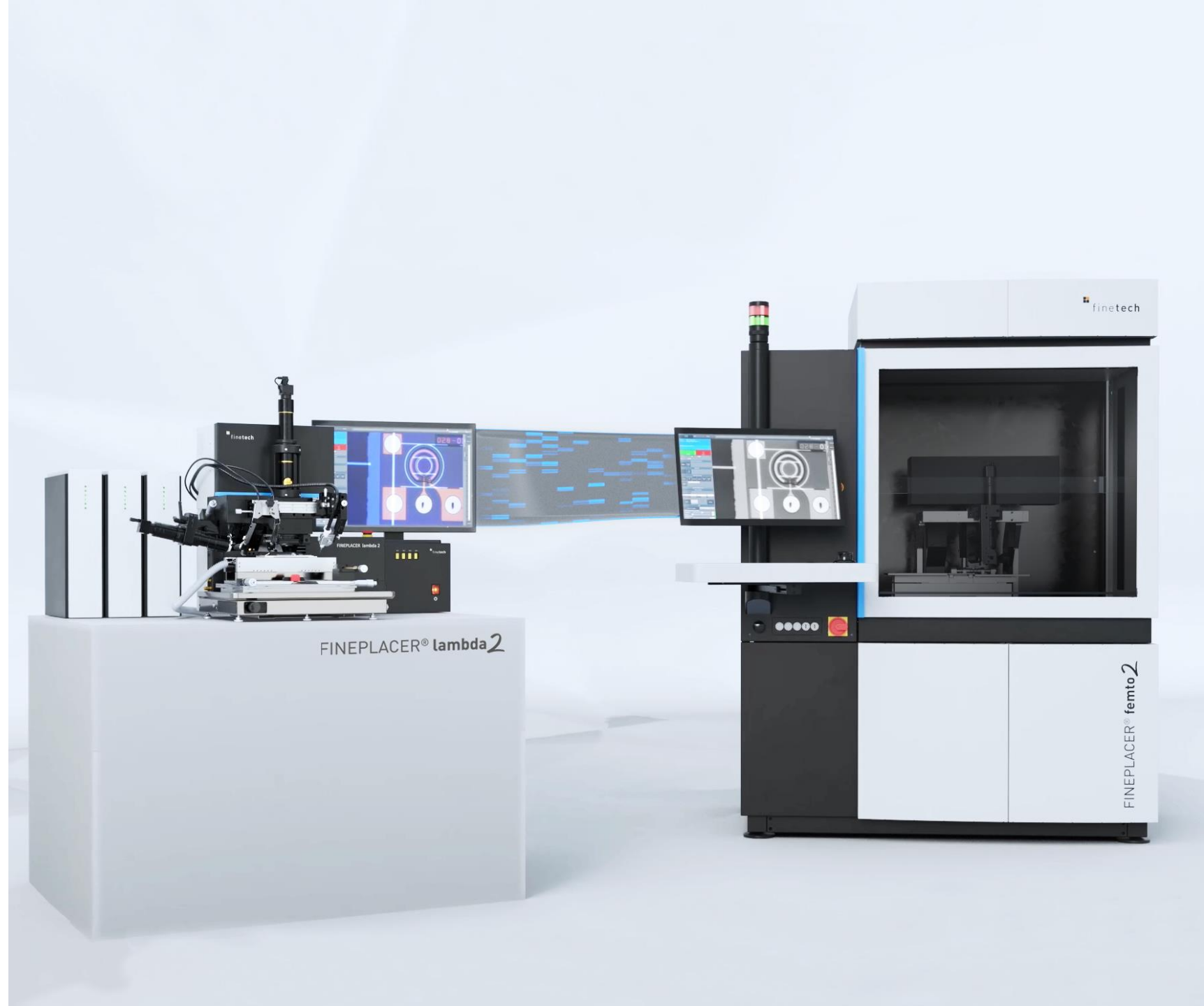
High Degree of Modularity

- » High variety of module combinations
- » Various technologies for multi-stage application
- » Capability to retrofit additional modules at any time



Process Transfer

- » Easy transfer of qualified processes from R&D to Production
- » Compatible software
- » Same process tool basis



FINEPLACER femto2

femto2 is a fully-automated die bonder with a placement accuracy of $0.3 \mu\text{m}$ @ 3 sigma that offers unrivaled flexibility for prototyping & production environments.



FINEPLACER femto^{blu}

femto^{blu} is a fully-automated die bonder with a placement accuracy of 2.0 μm @ 3 sigma and ultra-low bonding force capability for photonic applications.

[LINK TO VIDEO femto^{blu}](#)

Thank You!

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